

3C930 U.S. PTO  
10/064644



# U.S. UTILITY Patent Application

PATENT NUMBER and  
ISSUE DATE

2112

APPL NUM 10064644	FILING DATE 08/02/2002	CLASS 257	SUBCLASS 77E	GAU 281T	EXAMINER 3826 ELK/llaw
<b>**APPLICANTS:</b> Hsu Chi-Hsing;					
<b>**CONTINUING DATA VERIFIED:</b>					
<b>** FOREIGN APPLICATIONS VERIFIED:</b> TAIWAN 91208321 06/05/2002					
PG-PUB <input type="checkbox"/>		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed		<input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO	
35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no		9223-US-PA	
Verified and Acknowledged Examiners's initials					
TITLE : Flip-chip package substrate and flip chip die					

U.S. DEPT. OF COMM. PAT. & TM. PTO-436L (Rev. 12-97)

<b>NOTICE OF ALLOWANCE MAILED</b>		<b>CLAIMS ALLOWED</b>	
		Total Claims	Print Claim for O.G.
<b>ISSUE FEE</b>		<b>DRAWING</b>	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		Application Examiner	
		<b>PREPARED FOR ISSUE</b>	
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